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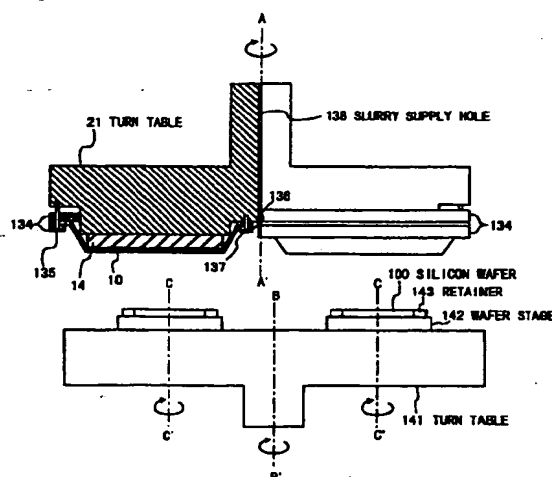
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(54) Polishing pad and apparatus for polishing a semiconductor wafer

(57) An apparatus for polishing a semiconductor wafer includes a polishing pad to be in contact with the semiconductor wafer; a turn table which rotates the polishing pad; and an elastic member which is arranged between the turn table and the polishing pad. The polishing pad includes a polishing layer which is made of a material having a good characteristic of slurry holding; and a support layer which is made of a rigid material having an optimum thickness to prevent the polishing layer from loosening. The polishing pad is attached to the turn table by a stretch-holding technique without adhesive bonding.

FIG. 1



EP 0 845 328 A3



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## EUROPEAN SEARCH REPORT

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DOCUMENTS CONSIDERED TO BE RELEVANT					
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.6)		
D, Y	PATENT ABSTRACTS OF JAPAN vol. 018, no. 065 (M-1554), 3 February 1994 & JP 05 285825 A (SUMITOMO METAL IND LTD), 2 November 1993 * abstract *	1-7, 12-16	B24B37/04 B24D13/14 B24D3/28		
Y	EP 0 555 660 A (WESTECH INC ;RODEL INC (US)) 18 August 1993 * column 6, line 57 - column 7, line 44 *	1-7, 12-16			
D, A	US 5 212 910 A (BREIVOGEL ET AL.) 25 May 1993 * column 4, line 26 - line 68 *	1, 12, 13			
A	PATENT ABSTRACTS OF JAPAN vol. 008, no. 107 (E-245), 19 May 1984 & JP 59 022329 A (NIPPON DENKI KK), 4 February 1984 * abstract *	1, 12, 13			
A	EP 0 658 401 A (SHINETSU HANDOTAI KK) 21 June 1995 * page 5, line 6 - page 6, line 13 *	1, 12, 13	<table border="1"> <thead> <tr> <th>TECHNICAL FIELDS SEARCHED (Int.Cl.6)</th> </tr> </thead> <tbody> <tr> <td>B24B B24D</td> </tr> </tbody> </table>	TECHNICAL FIELDS SEARCHED (Int.Cl.6)	B24B B24D
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The present search report has been drawn up for all claims					
Place of search <b>THE HAGUE</b>		Date of completion of the search <b>30 October 1998</b>	Examiner <b>Garella, M</b>		
<b>CATEGORY OF CITED DOCUMENTS</b> X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document		T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			

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